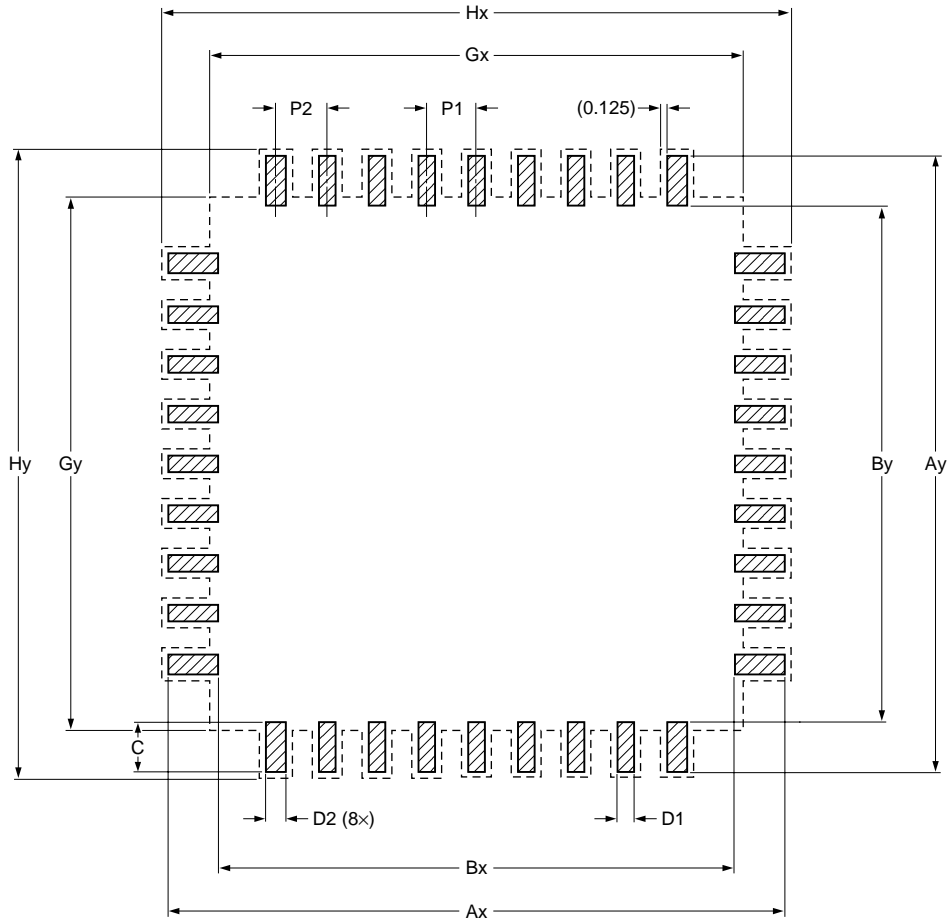



Footprint information for reflow soldering of LQFP64 package

SOT414-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.400	0.430	9.700	9.700	7.300	7.300	1.200	0.240	0.300	7.500	7.500	9.950	9.950